

**AMENDMENTS TO THE CLAIMS**

Please amend the claims as follows:

Claim 1 (Currently Amended): A flip chip mounting method comprising the steps of:

(a) preparing a chip including a pad covered with an insulation film;  
(b) selectively removing said insulation film over said pad to expose said pad;  
(c) after said step (b), forming a polyimide film including a first opening for exposing said pad, on said insulation film;

(d) filling said first opening to form a solder bump on said pad; and

(e) filling an underfill resin between an assembly substrate and said chip, for bonding said assembly substrate and said chip with said solder bump interposed therebetween,

wherein

said chip prepared in said step (a) further includes a fuse covered with said insulation film,

said step (b) further includes the step of selectively removing said insulation film above said fuse, and

said polyimide film formed in said step (c) further includes a second opening formed above said fuse.

Claim 2 (Canceled).

Claim 3 (Currently Amended): The flip chip mounting method according to claim claim 1 claim 2, wherein

    said insulation film is a passivation film in which an oxide film and a nitride film are stacked in this order, and

step (b) includes the steps of:

(b-1) selectively removing said nitride film above said pad and selectively removing said nitride film above said fuse; and  
(b-2) after said step (b-1), selectively removing said oxide film above said pad, for exposing said pad.

Claim 4 (Canceled).

Claim 5 (Currently Amended): The flip chip mounting method according to claim 1 claim 2, wherein

said insulation film is a passivation film in which an oxide film and a nitride film are stacked in this order, and

said step (b) further includes the steps of:

(b-3) selectively removing said nitride film and oxide film over said pad, for exposing said pad; and

(b-4) selectively removing said nitride film above said fuse using a mask which covers said pad as exposed.

Claim 6 (New): The flip chip mounting method according to claim 1, wherein

said step (b) further includes the steps of:

(b-10) forming a resist including a predetermined opening on said insulation film;

(b-11) selectively removing said insulation film over said pad and said insulation film above said fuse, for exposing said pad, by etching using said resist as a mask; and

(b-12) removing said resist after said step (b-11).